



GreenFET3 SLG59M1618V

Layout Guide

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Description

The SLG59M1618V is a 19 m Ω , ~ 2 A single-channel load switch that is able to switch 0.85 V to 5.5 V power rails. The product is packaged in an ultrasmall 1 x 1.4 mm package.

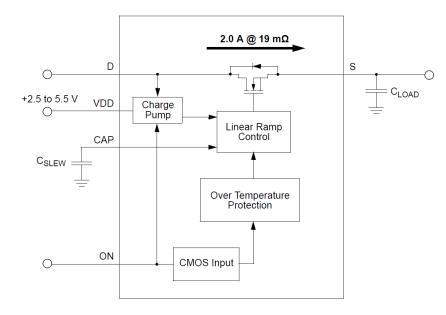


Figure 1: SLG59M1618V Block Diagram

This layout guide provides some important information about the PCB layout of SLG59M1618V applications.

SILEGO FC-TDFN 1.0x1.4-6L PKG

Unit: um

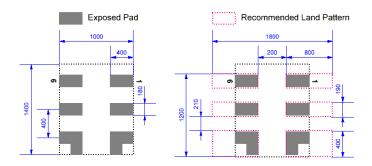


Figure 2. SLG59M1618V Package Dimensions and Recommended Land Pattern

Please solder your SLG59M1618V here

VDD GFET3 Evaluation Board #7 Ct C Silego Cchnology CAP/RILIN

VDD C23

D_SENSE2 U2 S_SENSE2

D_SENSE3 U3 S_SENSE3

D_SENSE3 U4 S_SENSE4

R4

D_SENSE3 U5 S_SENSE4

RA

28mm

Figure 3. SLG59M1618V Evaluation Test Board

Note: Evaluation board has D_Sense and S_Sense pads. Please use them only for RDS(ON) evaluation.

2. Power and Ground Planes

- 2.1. The VDD pin needs are 0.1 uF and 10 uF external capacitors to smooth pulses from the power supply. Locate these capacitors close to PIN1.
- 2.2. The trace length from the control IC to the ON pin should be as short as possible and must avoid crossing this trace with power rails.
- 2.3. The D/VIN and S/VOUT pins carry significant current. Please note how the D/VIN and S/VOUT pads are placed directly on the power planes in Figure 3, which minimizes the Rds(ON) associated with long, narrow traces. The D/VIN, S/VOUT and GND pins dissipate most of the heat generated during high-load current condition. The layout shown in Figure 3 is illustrating a proper solution for heat to transfer as efficiently as possible out of the device.
- 2.4. Place the power rail ramp capacitor as close as possible to the CAP pin to avoid/reduce the effect of parasitic mount capacitance.
- 2.5. The GND pin (PIN6) should be connected to GND.
- 2.6. 2 oz. copper is recommended for higher currents.